

PRELIMINARY DATA SHEET

NEC**MOS INTEGRATED CIRCUIT**

μ PD4264800, 4265800

**64 M-BIT DYNAMIC RAM
8 M-WORD BY 8-BIT, FAST PAGE MODE**

Description

The μ PD4264800, 4265800 are 8,388,608 words by 8 bits dynamic CMOS RAMs. The fast page mode capability realize high speed access and low power consumption.

These are packaged in 32-pin plastic TSOP(II) and 32-pin plastic SOJ.

Features

- 8,388,608 words by 8 bits organization
- Fast access and cycle time
- Single +3.3 V ± 0.3 V power supply

Part number	Power consumption		Access time (MAX.)	R/W cycle time (MIN.)	Fast page mode cycle time (MIN.)
	Active (MAX.)	Standby(MAX.)			
μ PD4264800-A50	378 mW	1.80 mW (CMOS level input)	50 ns	90 ns	35 ns
μ PD4265800-A50	486 mW		60 ns	110 ns	40 ns
μ PD4264800-A60	342 mW		70 ns	130 ns	45 ns
μ PD4265800-A60	414 mW		80 ns	150 ns	50 ns
μ PD4264800-A70	306 mW				
μ PD4265800-A70	378 mW				
μ PD4264800-A80	270 mW				
μ PD4265800-A80	342 mW				

- CAS before RAS refresh, RAS only refresh, Hidden refresh

Part number	Row address	Column address	Refresh	Refresh cycle
μ PD4264800	A0 - A12	A0 - A9	RAS only refresh, Normal read/write	8,192 cycles/64 ms
			CAS before RAS refresh, Hidden refresh	4,096 cycles/64 ms
μ PD4265800	A0 - A11	A0 - A10	RAS only refresh, Normal read/write,	4,096 cycles/64 ms
			CAS before RAS refresh, Hidden refresh	

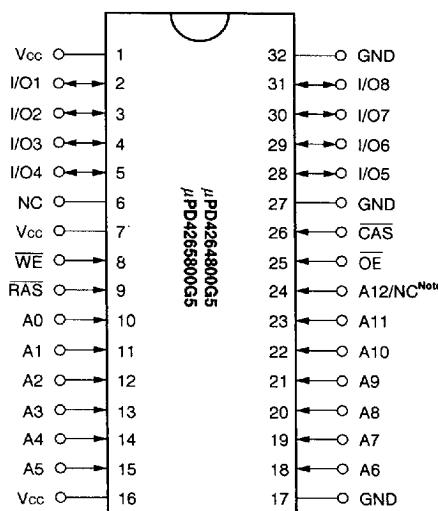
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Ordering Information

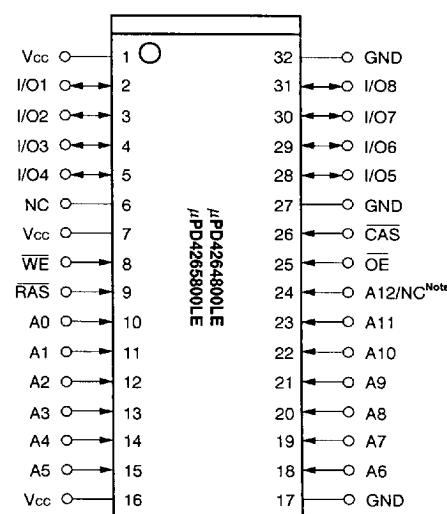
Part number	Access time (MAX.)	Package	Refresh
μ PD4264800G5-A50	50 ns	32-pin plastic TSOP (II) (400 mil)	CAS before \overline{RAS} refresh RAS only refresh Hidden refresh
μ PD4264800G5-A60	60 ns		
μ PD4264800G5-A70	70 ns		
μ PD4264800G5-A80	80 ns		
μ PD4264800LE-A50	50 ns	32-pin plastic SOJ (400 mil)	Hidden refresh
μ PD4264800LE-A60	60 ns		
μ PD4264800LE-A70	70 ns		
μ PD4264800LE-A80	80 ns		
μ PD4265800G5-A50	50 ns	32-pin plastic TSOP (II) (400 mil)	Hidden refresh
μ PD4265800G5-A60	60 ns		
μ PD4265800G5-A70	70 ns		
μ PD4265800G5-A80	80 ns		
μ PD4265800LE-A50	50 ns	32-pin plastic SOJ (400 mil)	Hidden refresh
μ PD4265800LE-A60	60 ns		
μ PD4265800LE-A70	70 ns		
μ PD4265800LE-A80	80 ns		

Pin Configurations (Marking Side)

32-pin Plastic TSOP (II) (400 mil)



32-pin Plastic SOJ (400 mil)

**Note** A12 ... μPD4264800

NC ... μPD4265800

- A0 to A12 : Address Inputs
- I/O1 to I/O8 : Data Inputs/Outputs
- RAS : Row Address Strobe
- CAS : Column Address Strobe
- WE : Write Enable
- OE : Output Enable
- Vcc : Power Supply
- GND : Ground
- NC : No Connection

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Input/Output Pin Functions

The μ PD4264800, 4265800 have input pins $\overline{\text{RAS}}$, $\overline{\text{CAS}}$, $\overline{\text{WE}}$, $\overline{\text{OE}}$, Address^{Note} and input/output pins I/O1 to I/O8.

Pin name	Input/Output	Function
$\overline{\text{RAS}}$ (Row address strobe)	Input	$\overline{\text{RAS}}$ activates the sense amplifier by latching a row address and selecting a corresponding word line. It refreshes memory cell array of one line selected by the row address. It also selects the following function. • $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh
$\overline{\text{CAS}}$ (Column address strobe)	Input	$\overline{\text{CAS}}$ activates data input/output circuit by latching column address and selecting a digit line connected with the sense amplifier.
A0 to A _x ^{Note} (Address inputs)	Input	Address bus. Input total 23-bit of address signal, upper bits and lower bits ^{Note} in sequence (address multiplex method). Therefore, one word is selected from 8,388,608-word by 8-bit memory cell array. In actual operation, latch row address by specifying row address and activating $\overline{\text{RAS}}$. Then, switch the address bus to column address and activate $\overline{\text{CAS}}$. Each address is taken into the device when $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ are activated. Therefore, the address input setup time (t_{ASR} , t_{ASC}) and hold time (t_{RAH} , t_{CAH}) are specified for the activation of $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$.
$\overline{\text{WE}}$ (Write enable)	Input	Write control signal. Write operation is executed by activating $\overline{\text{RAS}}$, $\overline{\text{CAS}}$ and $\overline{\text{WE}}$.
$\overline{\text{OE}}$ (Output enable)	Input	Read control signal. Read operation can be executed by activating $\overline{\text{RAS}}$, $\overline{\text{CAS}}$ and $\overline{\text{OE}}$. If $\overline{\text{WE}}$ is activated during read operation, $\overline{\text{OE}}$ is to be ineffective in the device. Therefore, read operation cannot be executed.
I/O1 to I/O8 (Data inputs/outputs)	Input/Output	8-bit data bus. I/O1 to I/O8 are used to input/output data.

Note

Part number	Address inputs	Upper bits	Lower bits
μ PD4264800	A0-A12	13	10
μ PD4265800	A0-A11	12	11

Electrical Specifications (Preliminary)

- All voltages are referenced to GND.
- After power up($V_{CC} \geq V_{CC(MIN.)}$), wait more than 100 μ s (\overline{RAS} , \overline{CAS} inactive) and then, execute eight \overline{CAS} before \overline{RAS} or \overline{RAS} only refresh cycles as dummy cycles to initialize internal circuit.

Absolute Maximum Ratings

Parameter	Symbol	Condition	Rating	Unit
Voltage on any pin relative to GND	V_T		-0.5 to +4.6	V
Supply voltage	V_{CC}		-0.5 to +4.6	V
Output current	I_O		20	mA
Power dissipation	P_D		1	W
Operating ambient temperature	T_A		0 to +70	°C
Storage temperature	T_{STG}		-55 to +125	°C

Caution Exposing the device to stress above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply voltage	V_{CC}		3.0	3.3	3.6	V
High level input voltage	V_{IH}		2.0		$V_{CC} + 0.3$	V
Low level input voltage	V_{IL}		-0.3		+0.8	V
Operating ambient temperature	T_A		0		70	°C

Capacitance ($T_A = 25$ °C, $f = 1$ MHz)

Parameter	Symbol	Test condition	MIN.	TYP.	MAX.	Unit
Input capacitance	C_{I1}	Address			5	pF
	C_{I2}	\overline{RAS} , \overline{CAS} , \overline{WE} , \overline{OE}			7	
Data input/output capacitance	C_{IO}	I/O			7	pF

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DC Characteristics (Recommended operating conditions unless otherwise noted)

[μPD4264800]

Parameter	Symbol	Test condition	MIN.	MAX.	Unit	Notes
Operating current	Icc1	RAS, CAS cycling	tRAC = 50 ns	105	mA	1, 2, 3
		tRC = tRC (MIN.)	tRAC = 60 ns	95		
		Io = 0 mA	tRAC = 70 ns	85		
			tRAC = 80 ns	75		
Standby current	Icc2	RAS, CAS $\geq V_{IH}$ (MIN.), Io = 0 mA		1.0	mA	
		RAS, CAS $\geq V_{CC} - 0.2$ V, Io = 0 mA		0.5		
RAS only refresh current	Icc3	RAS cycling, CAS $\geq V_{IH}$ (MIN.)	tRAC = 50 ns	105	mA	1, 2, 3, 4
		tRC = tRC (MIN.), Io = 0 mA	tRAC = 60 ns	95		
			tRAC = 70 ns	85		
			tRAC = 80 ns	75		
Operating current (Fast page mode)	Icc4	RAS $\leq V_{IL}$ (MAX.), CAS cycling	tRAC = 50 ns	85	mA	1, 2, 5
		tPC = tPC (MIN.), Io = 0 mA	tRAC = 60 ns	75		
			tRAC = 70 ns	65		
			tRAC = 80 ns	55		
CAS before RAS refresh current	Icc5	RAS cycling	tRAC = 50 ns	135	mA	1, 2
		tRC = tRC (MIN.)	tRAC = 60 ns	115		
		Io = 0 mA	tRAC = 70 ns	105		
			tRAC = 80 ns	95		
Input leakage current	I _{I(L)}	V _I = 0 to 3.6 V All other pins not under test = 0 V	-5	+5	μA	
Output leakage current	I _{O(L)}	V _O = 0 to 3.6 V Output is disabled (Hi-Z)	-5	+5	μA	
High level output voltage	V _{OH}	Io = -2.0 mA	2.4		V	
Low level output voltage	V _{OL}	Io = +2.0 mA		0.4	V	

[μ PD4265800]

Parameter	Symbol	Test condition	MIN.	MAX.	Unit	Notes
Operating current	Icc1	RAS, CAS cycling	tRAC = 50 ns	135	mA	1, 2, 3
		tRC = tRC (MIN.)	tRAC = 60 ns	115		
		Io = 0 mA	tRAC = 70 ns	105		
			tRAC = 80 ns	95		
Standby current	Icc2	RAS, CAS $\geq V_{IH}$ (MIN.), Io = 0 mA		1.0	mA	
		RAS, CAS $\geq V_{CC} - 0.2$ V, Io = 0 mA		0.5		
RAS only refresh current	Icc3	RAS cycling, CAS $\geq V_{IH}$ (MIN.)	tRAC = 50 ns	135	mA	1, 2, 3, 4
		tRC = tRC (MIN.), Io = 0 mA	tRAC = 60 ns	115		
			tRAC = 70 ns	105		
			tRAC = 80 ns	95		
Operating current (Fast page mode)	Icc4	RAS $\leq V_{IL}$ (MAX.), CAS cycling	tRAC = 50 ns	85	mA	1, 2, 5
		tPC = tPC (MIN.), Io = 0 mA	tRAC = 60 ns	75		
			tRAC = 70 ns	65		
			tRAC = 80 ns	55		
CAS before RAS refresh current	Icc5	RAS cycling	tRAC = 50 ns	135	mA	1, 2
		tRC = tRC (MIN.)	tRAC = 60 ns	115		
		Io = 0 mA	tRAC = 70 ns	105		
			tRAC = 80 ns	95		
Input leakage current	Ii (I)	Vi = 0 to 3.6 V All other pins not under test = 0 V	-5	+5	μ A	
Output leakage current	Io (I)	Vo = 0 to 3.6 V Output is disabled (Hi-Z)	-5	+5	μ A	
High level output voltage	Voh	Io = -2.0 mA	2.4		V	
Low level output voltage	Vol	Io = +2.0 mA		0.4	V	

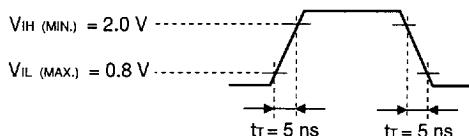
Notes 1. Icc1, Icc3, Icc4 and Icc5 depend on cycle rates (tRC and tPC).

2. Specified values are obtained with outputs unloaded.
3. Icc1 and Icc3 are measured assuming that address can be changed once or less during RAS $\leq V_{IL}$ (MAX.) and CAS $\geq V_{IH}$ (MIN.).
4. Icc3 is measured assuming that all column address inputs are held at either high or low.
5. Icc4 is measured assuming that all column address inputs are switched only once during each fast page cycle.

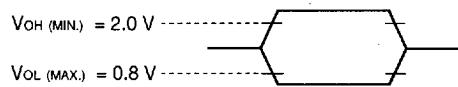
AC Characteristics (Recommended Operating Conditions unless otherwise noted)

AC Characteristics Test Conditions

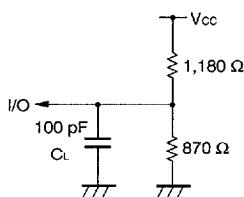
(1) Input timing specification



(2) Output timing specification



(3) Output load condition



Common to Read, Write, Read Modify Write Cycle

Parameter	Symbol	t _{RAC} = 50 ns		t _{RAC} = 60 ns		t _{RAC} = 70 ns		t _{RAC} = 80 ns		Unit	Notes
		MIN.	MAY.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read / Write cycle time	t _{RC}	90	—	110	—	130	—	150	—	ns	
RAS precharge time	t _{RP}	30	—	40	—	50	—	60	—	ns	
CAS precharge time	t _{CPN}	8	—	10	—	10	—	10	—	ns	
RAS pulse width	t _{RAS}	50	10,000	60	10,000	70	10,000	80	10,000	ns	
CAS pulse width	t _{CAS}	13	10,000	15	10,000	18	10,000	20	10,000	ns	
RAS hold time	t _{RSH}	13	—	15	—	18	—	20	—	ns	
CAS hold time	t _{CSH}	50	—	60	—	70	—	80	—	ns	
RAS to CAS delay time	t _{RCDD}	18	37	20	45	20	52	25	60	ns	1
RAS to column address delay time	t _{RAD}	13	25	15	30	15	35	17	40	ns	1
CAS to RAS precharge time	t _{CRP}	5	—	5	—	5	—	5	—	ns	2
Row address setup time	t _{ASR}	0	—	0	—	0	—	0	—	ns	
Row address hold time	t _{RAH}	8	—	10	—	10	—	12	—	ns	
Column address setup time	t _{ASC}	0	—	0	—	0	—	0	—	ns	
Column address hold time	t _{CAH}	13	—	15	—	15	—	15	—	ns	
OE lead time referenced to RAS	t _{OES}	0	—	0	—	0	—	0	—	ns	
CAS to data setup time	t _{CLZ}	0	—	0	—	0	—	0	—	ns	
OE to data setup time	t _{OLZ}	0	—	0	—	0	—	0	—	ns	
OE to data delay time	t _{OED}	10	—	13	—	15	—	15	—	ns	
Transition time (rise and fall)	tr	3	50	3	50	3	50	3	50	ns	
Refresh time	t _{REF}	—	64	—	64	—	64	—	64	ms	

Notes 1. For read cycles, access time is defined as follows:

Input conditions	Access time	Access time from RAS
$t_{RAD} \leq t_{RAD}(\text{MAX.})$ and $t_{RCD} \leq t_{RCD}(\text{MAX.})$	$t_{RAC}(\text{MAX.})$	$t_{RAC}(\text{MAX.})$
$t_{RAD} > t_{RAD}(\text{MAX.})$ and $t_{RCD} \leq t_{RCD}(\text{MAX.})$	$t_{AA}(\text{MAX.})$	$t_{RAD} + t_{AA}(\text{MAX.})$
$t_{RCD} > t_{RCD}(\text{MAX.})$	$t_{CAC}(\text{MAX.})$	$t_{RCD} + t_{CAC}(\text{MAX.})$

$t_{RAD}(\text{MAX.})$ and $t_{RCD}(\text{MAX.})$ are specified as reference points only; they are not restrictive operating parameters. They are used to determine which access time (t_{RAC} , t_{AA} or t_{CAC}) is to be used for finding out when data will be available. Therefore, the input conditions $t_{RAD} \geq t_{RAD}(\text{MAX.})$ and $t_{RCD} \geq t_{RCD}(\text{MAX.})$ will not cause any operation problems.

2. $t_{CRP}(\text{MIN.})$ requirement is applied to RAS, CAS cycles.

Read Cycle

Parameter	Symbol	$t_{RAC} = 50 \text{ ns}$		$t_{RAC} = 60 \text{ ns}$		$t_{RAC} = 70 \text{ ns}$		$t_{RAC} = 80 \text{ ns}$		Unit	Notes
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Access time from RAS	t_{RAC}	—	50	—	60	—	70	—	80	ns	1
Access time from CAS	t_{CAC}	—	13	—	15	—	18	—	20	ns	1
Access time from column address	t_{AA}	—	25	—	30	—	35	—	40	ns	1
Access time from OE	t_{OE}	—	13	—	15	—	18	—	20	ns	
Column address lead time referenced to RAS	t_{RAL}	25	—	30	—	35	—	40	—	ns	
Read command setup time	t_{RCS}	0	—	0	—	0	—	0	—	ns	
Read command hold time referenced to RAS	t_{RRH}	0	—	0	—	0	—	0	—	ns	2
Read command hold time referenced to CAS	t_{RCH}	0	—	0	—	0	—	0	—	ns	2
Output buffer turn-off delay time from OE	t_{OEZ}	0	10	0	13	0	15	0	15	ns	3
Output buffer turn-off delay time from CAS	t_{OFF}	0	10	0	13	0	15	0	15	ns	3

Notes 1. For read cycles, access time is defined as follows:

Input conditions	Access time	Access time from RAS
$t_{RAD} \leq t_{RAD}(\text{MAX.})$ and $t_{RCD} \leq t_{RCD}(\text{MAX.})$	$t_{RAC}(\text{MAX.})$	$t_{RAC}(\text{MAX.})$
$t_{RAD} > t_{RAD}(\text{MAX.})$ and $t_{RCD} \leq t_{RCD}(\text{MAX.})$	$t_{AA}(\text{MAX.})$	$t_{RAD} + t_{AA}(\text{MAX.})$
$t_{RCD} > t_{RCD}(\text{MAX.})$	$t_{CAC}(\text{MAX.})$	$t_{RCD} + t_{CAC}(\text{MAX.})$

$t_{RAD}(\text{MAX.})$ and $t_{RCD}(\text{MAX.})$ are specified as reference points only; they are not restrictive operating parameters. They are used to determine which access time (t_{RAC} , t_{AA} or t_{CAC}) is to be used for finding out when output data will be available. Therefore, the input conditions $t_{RAD} \geq t_{RAD}(\text{MAX.})$ and $t_{RCD} \geq t_{RCD}(\text{MAX.})$ will not cause any operation problems.

- 2.** Either $t_{RCH}(\text{MIN.})$ or $t_{RRH}(\text{MIN.})$ should be met in read cycles.
- 3.** $t_{OFF}(\text{MAX.})$ and $t_{OEZ}(\text{MAX.})$ define the time when the output achieves the condition of Hi-Z and is not referenced to V_{OH} or V_{OL} .

Write Cycle

Parameter	Symbol	trac = 50 ns		trac = 60 ns		trac = 70 ns		trac = 80 ns		Unit	Notes
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
WE hold time referenced to CAS	twch	8	—	10	—	10	—	15	—	ns	1
WE pulse width	twp	8	—	10	—	10	—	15	—	ns	1
WE lead time referenced to RAS	trwl	13	—	15	—	15	—	15	—	ns	
WE lead time referenced to CAS	towl	13	—	15	—	15	—	15	—	ns	
WE setup time	twcs	0	—	0	—	0	—	0	—	ns	2
OE hold time	toeh	0	—	0	—	0	—	0	—	ns	
Data-in setup time	tds	0	—	0	—	0	—	0	—	ns	3
Data-in hold time	tdh	10	—	10	—	15	—	15	—	ns	3

Notes 1. twp (MIN.) is applied to late write cycles or read modify write cycles. In early write cycles, twch (MIN.) should be met.

2. If twcs \geq twcs (MIN.), the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle.
3. tds (MIN.) and tdh (MIN.) are referenced to the CAS falling edge in early write cycles. In late write cycles and read modify write cycles, they are referenced to the WE falling edge.

Read Modify Write Cycle

Parameter	Symbol	trac = 50 ns		trac = 60 ns		trac = 70 ns		trac = 80 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read modify write cycle time	trwc	128	—	153	—	175	—	195	—	ns	
RAS to WE delay time	trwd	70	—	83	—	95	—	105	—	ns	1
CAS to WE delay time	tcwd	33	—	38	—	43	—	45	—	ns	1
Column address to WE delay time	tawd	45	—	53	—	60	—	65	—	ns	1

Note 1. If twcs \geq twcs (MIN.), the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle. If trwd \geq trwd (MIN.), tcwd \geq tcwd (MIN.), tawd \geq tawd (MIN.) and tcpwd \geq tcpwd (MIN.), the cycle is a read modify write cycle and the data out will contain data read from the selected cell. If neither of the above conditions is met, the state of the data out is indeterminate.

Fast Page Mode

Parameter	Symbol	tRAC = 50 ns		tRAC = 60 ns		tRAC = 70 ns		tRAC = 80 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Fast page mode cycle time	t _{PC}	35	—	40	—	45	—	50	—	ns	
Access time from CAS precharge	t _{ACP}	—	30	—	35	—	40	—	45	ns	
RAS pulse width	t _{RASP}	50	125,000	60	125,000	70	125,000	80	125,000	ns	
CAS precharge time	t _{CP}	8	—	10	—	10	—	10	—	ns	
RAS hold time from CAS precharge	t _{RHCP}	30	—	35	—	40	—	45	—	ns	
Read modify write cycle time	t _{PRWC}	73	—	83	—	90	—	95	—	ns	
CAS precharge to WE delay time	t _{CPWD}	50	—	58	—	65	—	70	—	ns	1

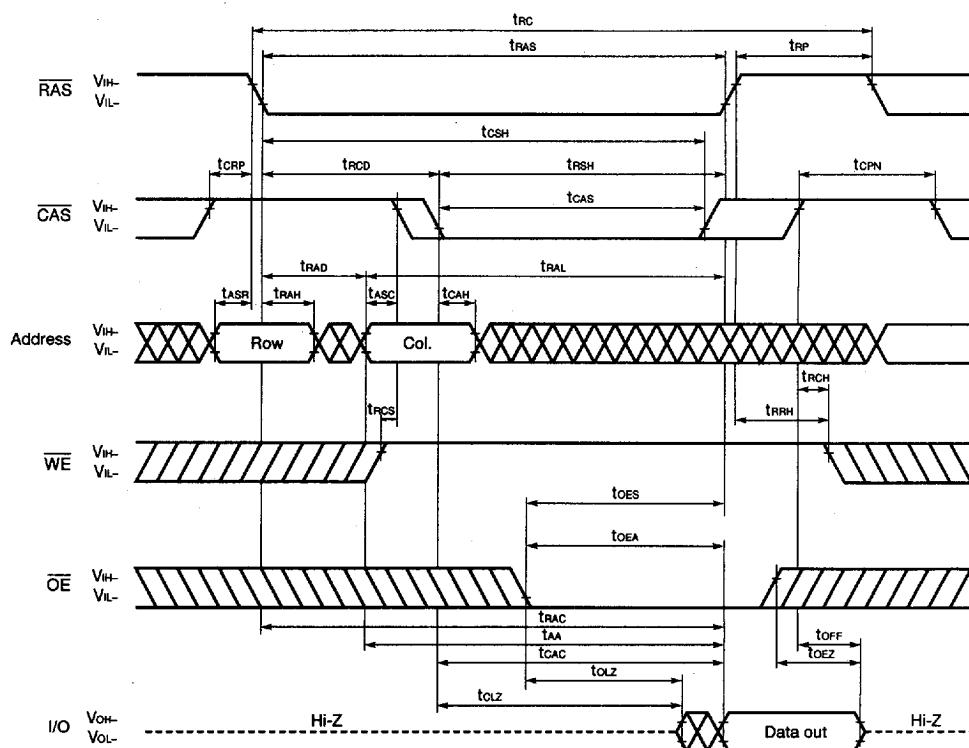
Note 1. If twcs \geq twcs (MIN.), the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle. If t_{RWD} \geq t_{RWD} (MIN.), t_{CWD} \geq t_{CWD} (MIN.), t_{AWD} \geq t_{AWD} (MIN.) and t_{CPWD} \geq t_{CPWD} (MIN.), the cycle is a read modify write cycle and the data out will contain data read from the selected cell. If neither of the above conditions is met, the state of the data out is indeterminate.

Refresh Cycle

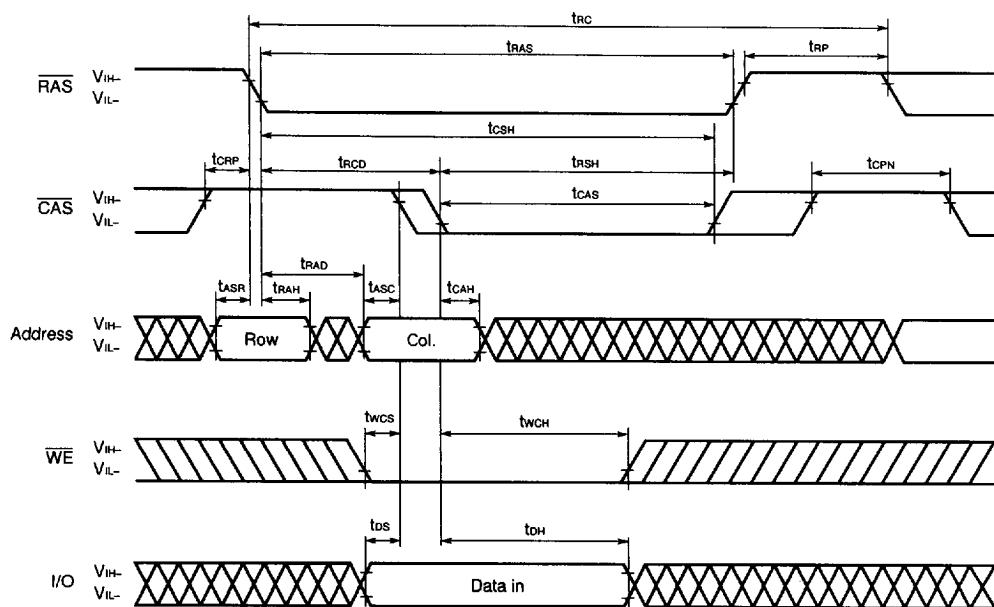
Parameter	Symbol	tRAC = 50 ns		tRAC = 60 ns		tRAC = 70 ns		tRAC = 80 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
CAS setup time	t _{CSR}	5	—	5	—	5	—	5	—	ns	
CAS hold time (CAS before RAS refresh)	t _{CHR}	10	—	10	—	10	—	10	—	ns	
RAS precharge CAS hold time	t _{RPC}	5	—	5	—	5	—	5	—	ns	
WE setup time	t _{WSR}	10	—	10	—	10	—	10	—	ns	
WE hold time	t _{WHR}	15	—	15	—	15	—	15	—	ns	

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Read Cycle



Early Write Cycle

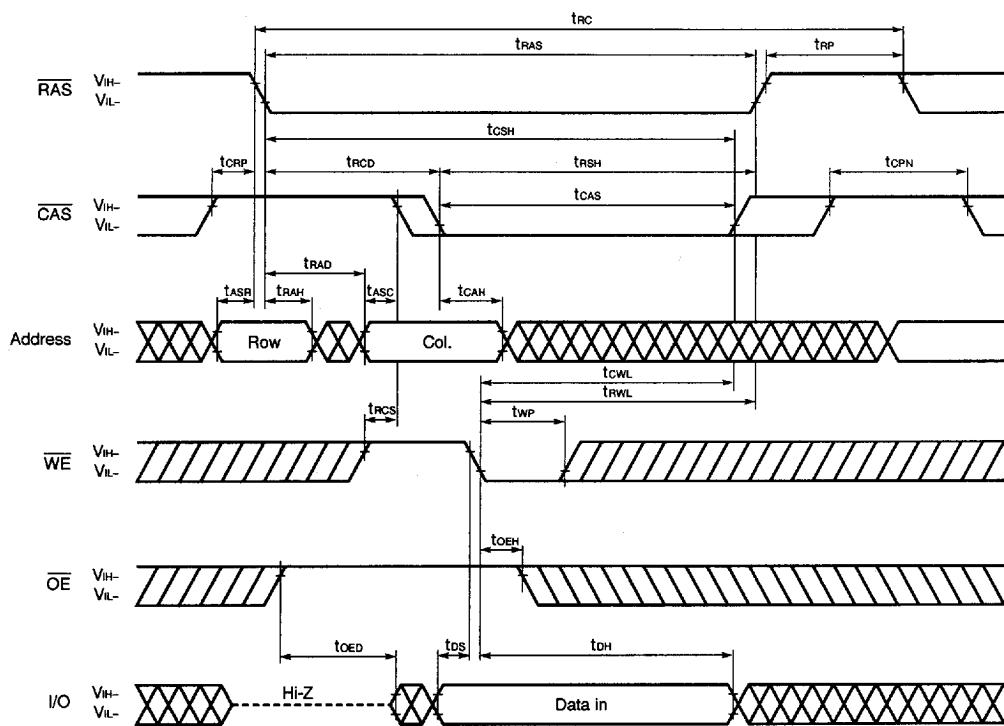


Remark OE: Don't care

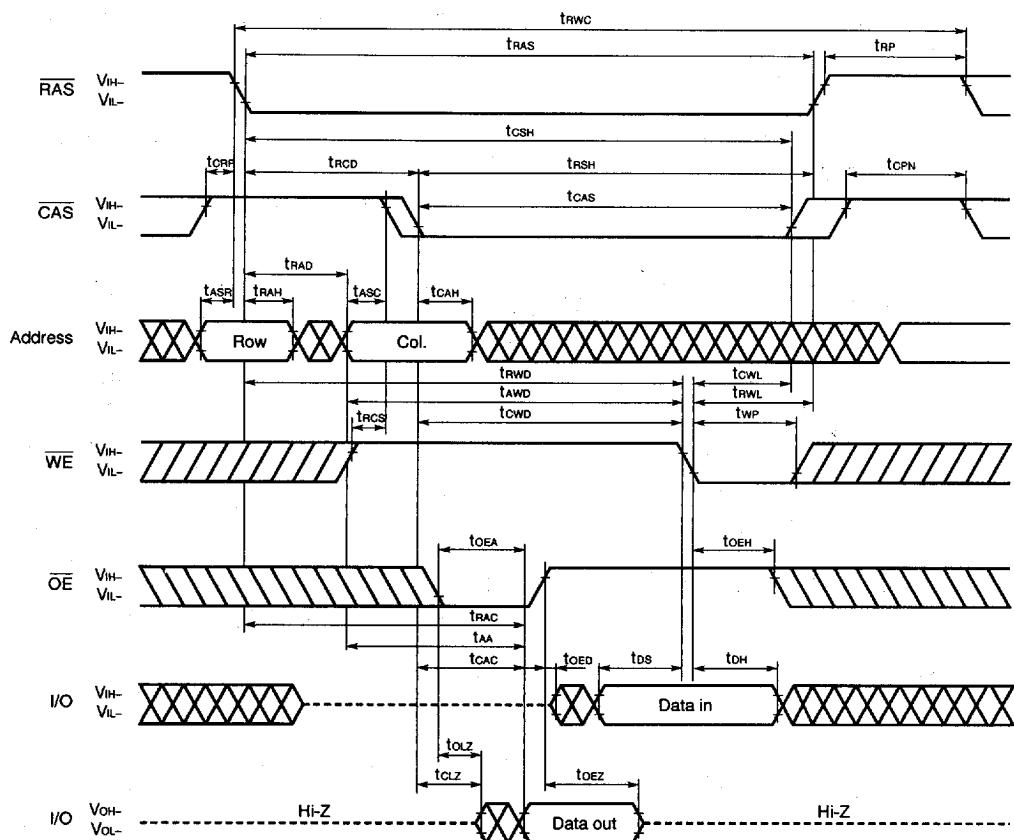
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Late Write Cycle



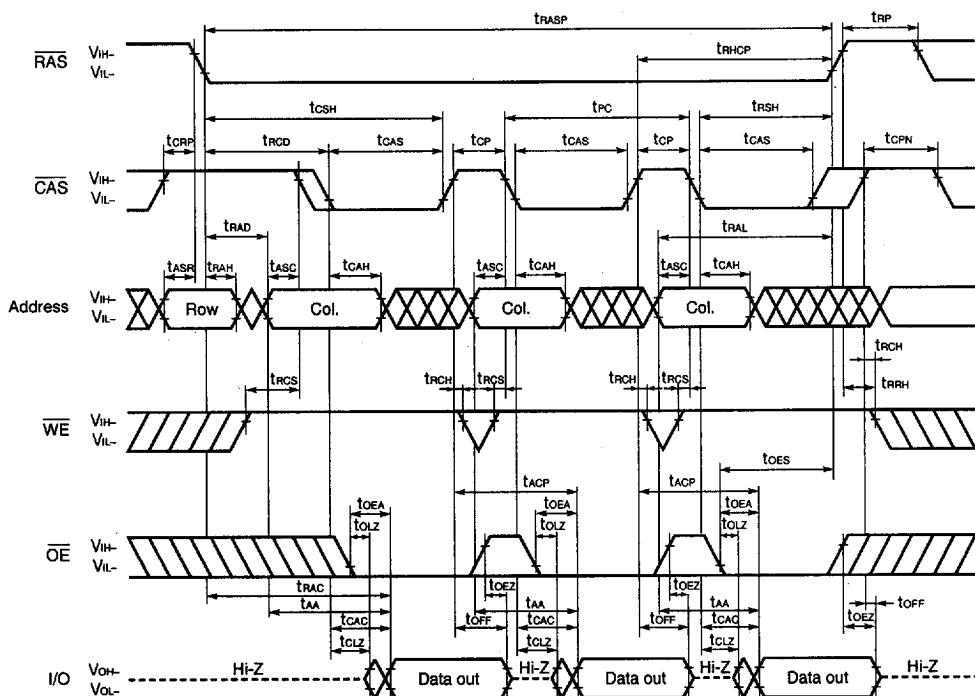
Read Modify Write Cycle



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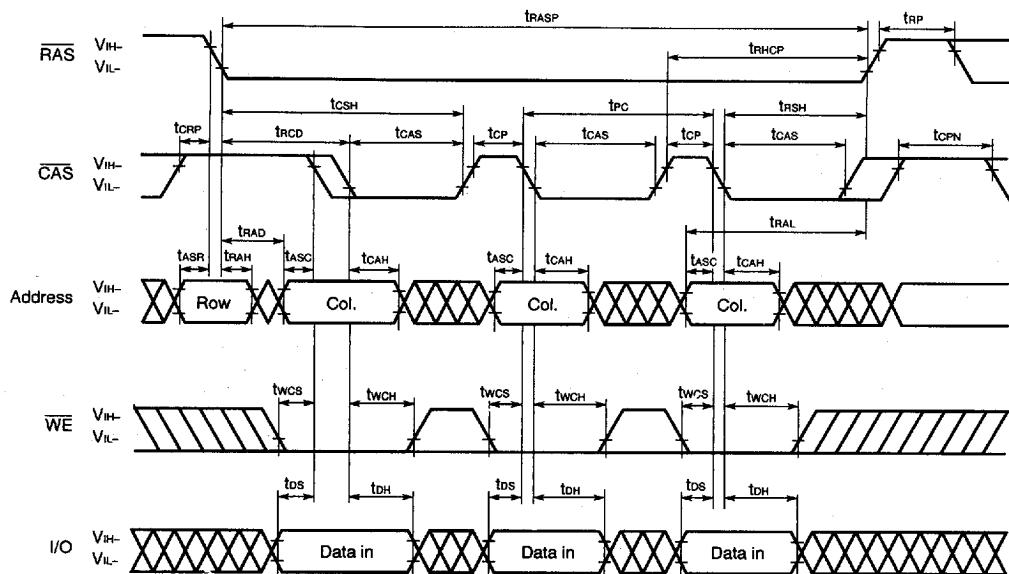
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Fast Page Mode Read Cycle



Remark In the fast page mode, read, write and read modify write cycles are available for each of the consecutive CAS cycles within the same RAS cycle.

Fast Page Mode Early Write Cycle



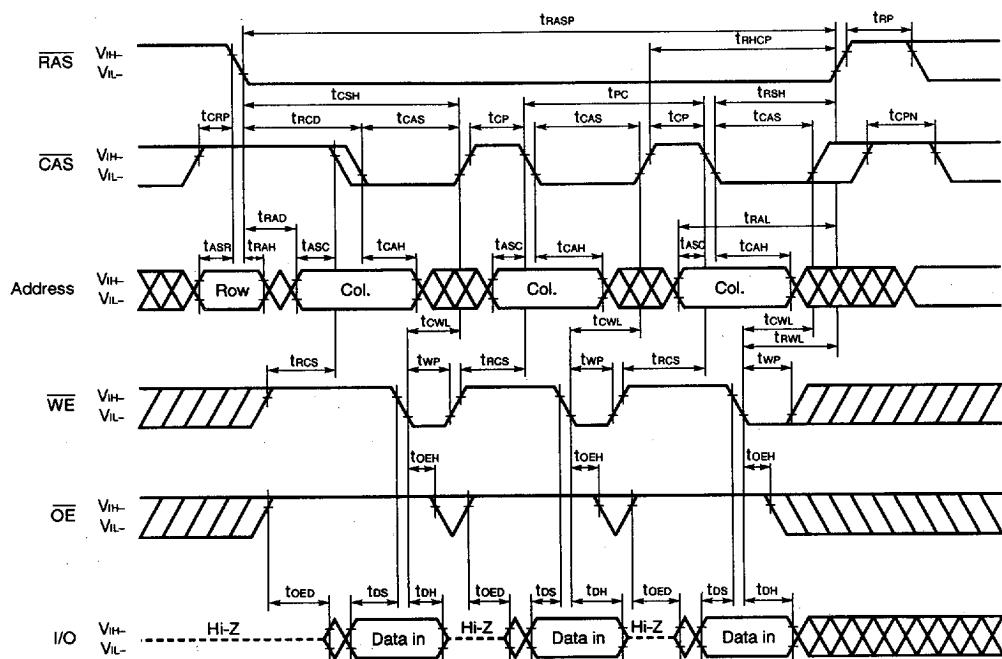
Remarks 1. \overline{OE} : Don't care

2. In the fast page mode, read, write and read modify write cycles are available for each of the consecutive \overline{CAS} cycles within the same \overline{RAS} cycle.

■ 6427525 0091438 T80 ■

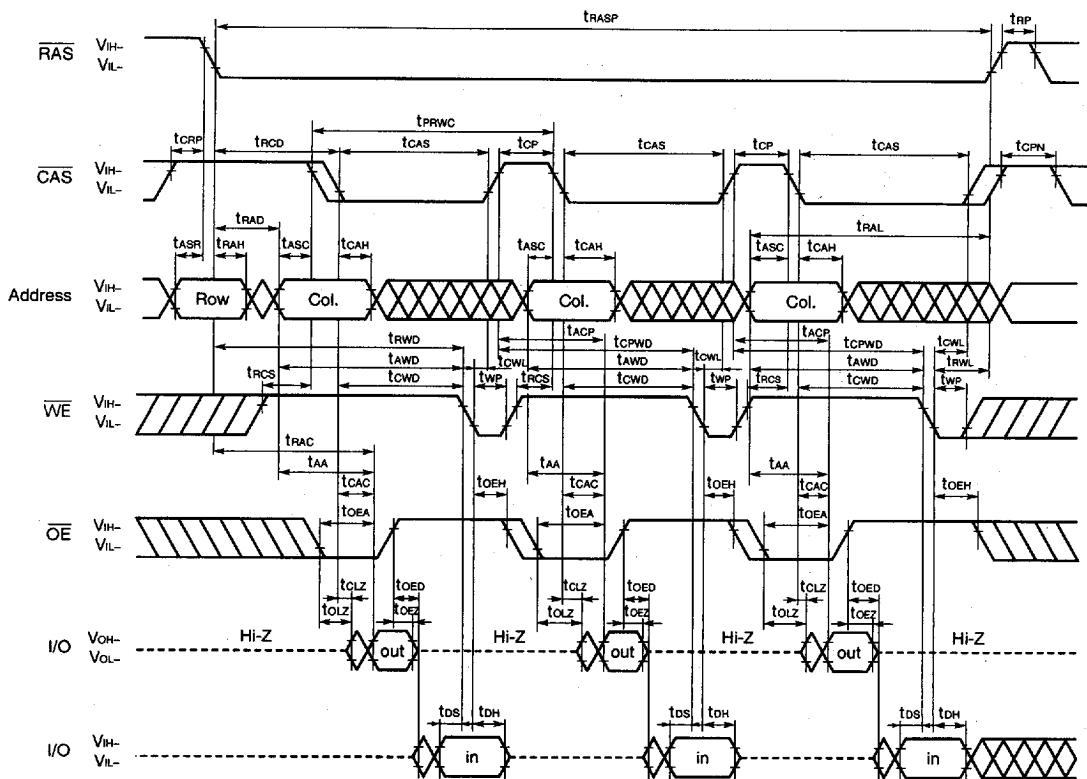
627

Fast Page Mode Late Write Cycle



Remark In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{\text{CAS}}$ cycles within the same $\overline{\text{RAS}}$ cycle.

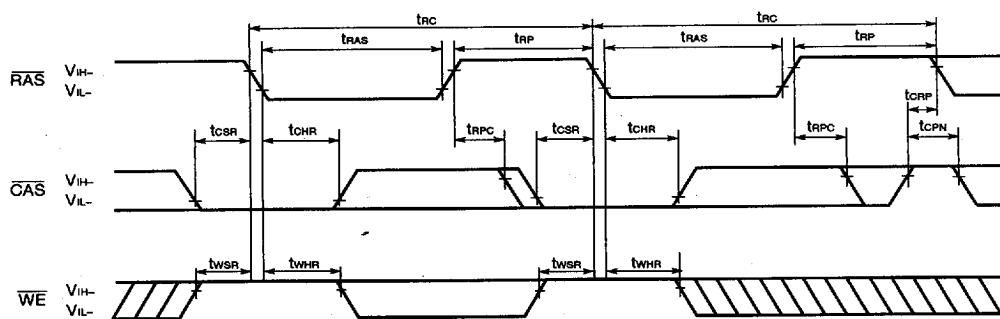
Fast Page Mode Read Modify Write Cycle



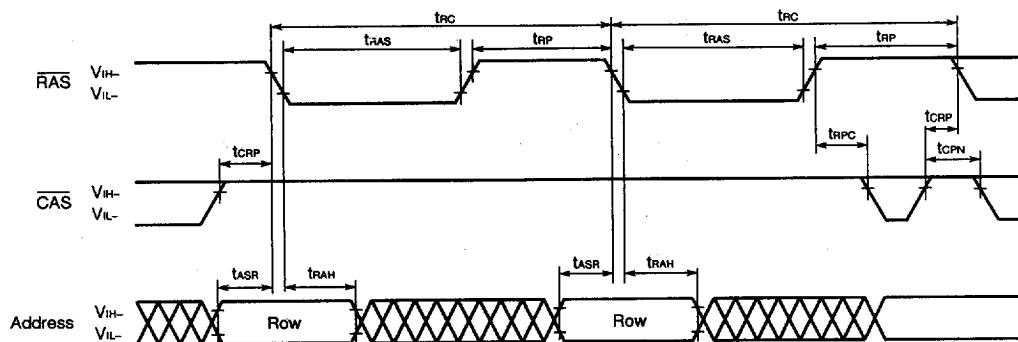
Remark In the fast page mode, read, write and read modify write cycles are available for each of the consecutive CAS cycles within the same RAS cycle.

■ 6427525 0091440 639 ■

629

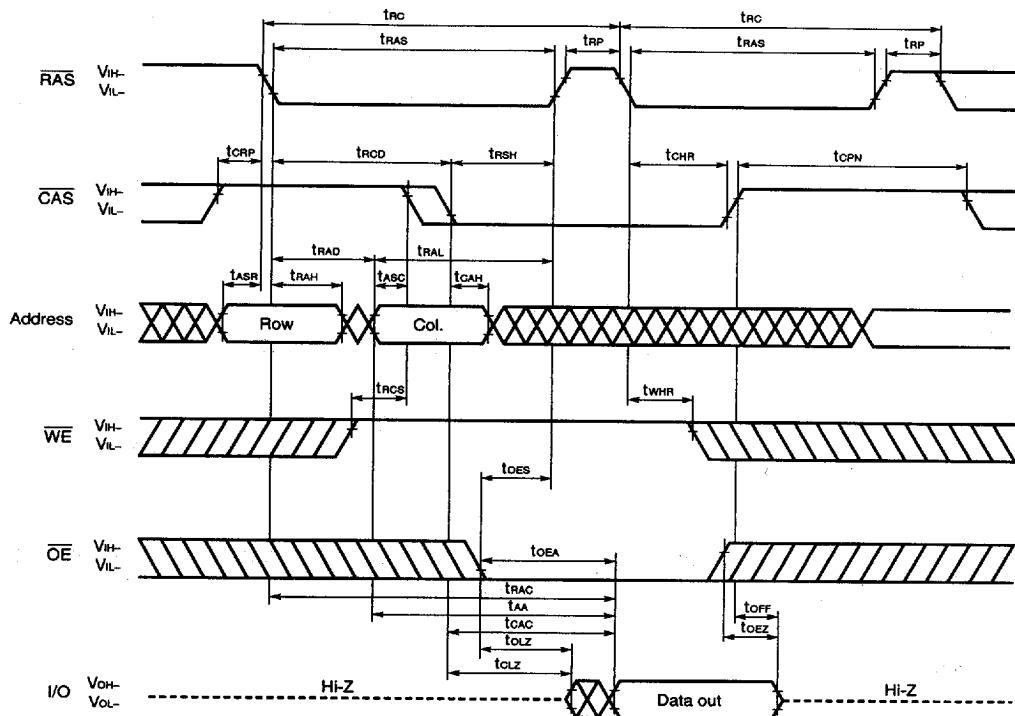
CAS Before RAS Refresh Cycle

Remark Address, \overline{OE} : Don't care I/O: Hi-Z

RAS Only Refresh Cycle

Remark WE, \overline{OE} : Don't care I/O: Hi-Z

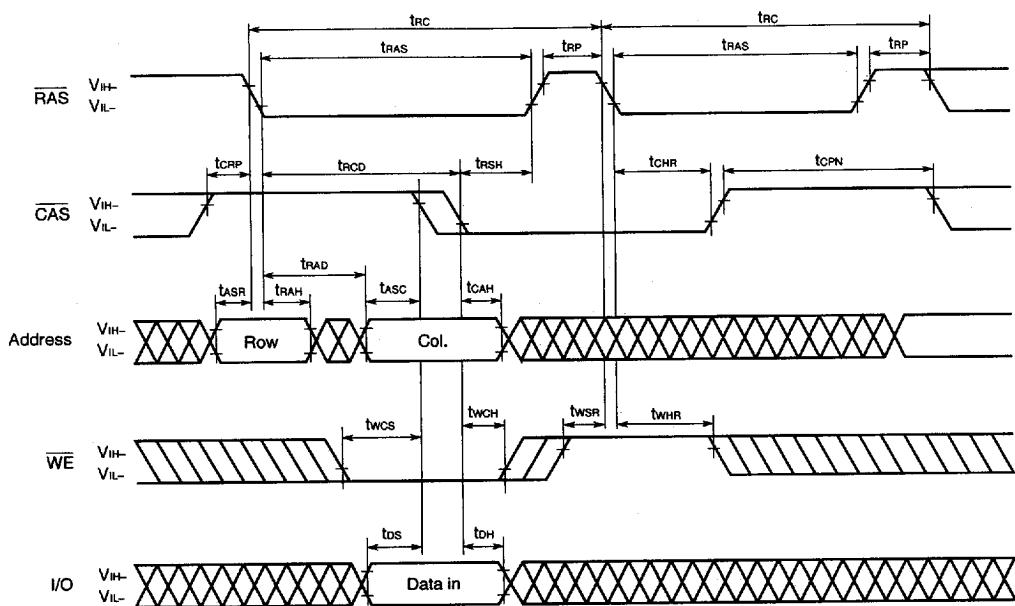
Hidden Refresh Cycle (Read)



■ 6427525 0091442 401 ■

631

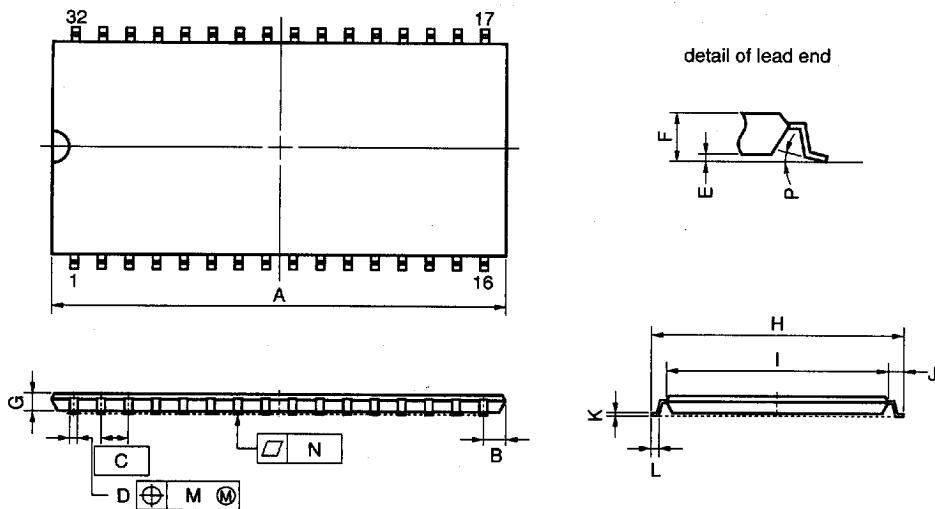
Hidden Refresh Cycle (Write)



Remark \overline{OE} : Don't care

Package Drawings

32PIN PLASTIC TSOP(II) (400 mil)



NOTE

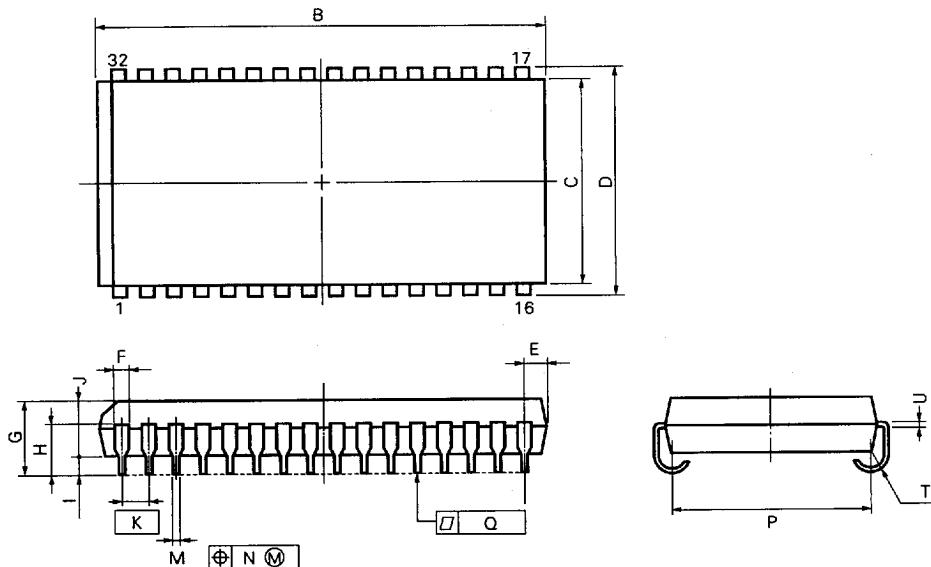
Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	21.17 MAX.	0.834 MAX.
B	1.075 MAX.	0.043 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	$0.42^{+0.08}_{-0.07}$	0.017 ± 0.003
E	0.1 ± 0.05	0.004 ± 0.002
F	1.2 MAX.	0.048 MAX.
G	0.97	0.038
H	11.76 ± 0.2	0.463 ± 0.008
I	10.16 ± 0.1	0.400 ± 0.004
J	0.8 ± 0.2	0.031 ± 0.009
K	$0.145^{+0.025}_{-0.015}$	0.006 ± 0.001
L	0.5 ± 0.1	0.020 ± 0.004
M	0.21	0.009
N	0.10	0.004
P	$3^{\circ} \pm 7^{\circ}$	$3^{\circ} \pm 7^{\circ}$

S32G5-50-7JD2

■ 6427525 0091444 284 ■

32 PIN PLASTIC SOJ (400 mil)

**NOTE**

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

P32LE-400A

ITEM	MILLIMETERS	INCHES
B	21.06 ± 0.2	0.829 ± 0.008
C	10.16	0.400
D	11.18 ± 0.2	0.440 ± 0.008
E	1.005 ± 0.1	$0.040^{+0.004}_{-0.005}$
F	0.74	0.029
G	3.5 ± 0.2	0.138 ± 0.008
H	2.545 ± 0.2	0.100 ± 0.008
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40 ± 0.10	$0.016^{+0.004}_{-0.005}$
N	0.12	0.005
P	9.4 ± 0.20	0.370 ± 0.008
Q	0.1	0.004
T	R 0.85	R 0.033
U	$0.20^{+0.10}_{-0.05}$	$0.008^{+0.004}_{-0.002}$

■ 6427525 0091445 110 ■